

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2003-050459

(43)Date of publication of application : 21.02.2003

(51)Int.Cl.

G03F 7/004  
G03F 7/031  
H05K 3/06  
H05K 3/18

(21)Application number : 2001-239622

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(22)Date of filing : 07.08.2001

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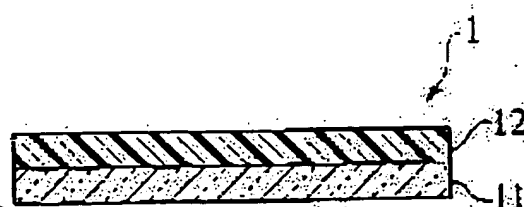
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(54) **PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ELEMENT, METHOD FOR PRODUCING RESIST PATTERN AND METHOD FOR PRODUCING PRINTED WIRING BOARD**

(57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a photosensitive resin composition excellent in photosensitivity, resolution, adhesion and solubility in a developing solution and a photosensitive element using the composition.

**SOLUTION:** The photosensitive resin composition comprises (A) a binder polymer, (B) a photopolymerizable monomer containing an ethylenically unsaturated group, (C) a polycyclic aromatic hydrocarbon, (D) a photopolymerization initiator and (E) a hydrogen donor. The photosensitive element is obtained by forming a resist layer comprising the photosensitive resin



composition on a support.

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## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of  
rejection]

[Kind of final disposal of application other than the  
examiner's decision of rejection or application  
converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of  
rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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